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	Subclass

ISSUE CLASSIFICATION



PATENT NUMBER

U.S. UTILITY Patent Application

 O.I.P.E.	PATENT DATE
SCANNED  Q.A.	

APPLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINER
09/902878		257	678+	28112527	CHAMBLISS

APPlicants

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TIME

Enhanced thermal dissipation integrated circuit package and method
of manufacturing enhanced thermal dissipation integrated circuit
package PTO-204
12/89

PTO-2040
12/99

ISSUING CLASSIFICATION

TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.				NOTICE OF ALLOWANCE MAILED	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent No. _____ _____				ISSUE FEE	
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.				Amount Due	Date Paid
				ISSUE BATCH NUMBER	

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